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# FQP12N60C / FQPF12N60C **600V N-Channel MOSFET**

#### **Features**

- 12A, 600V,  $R_{DS(on)}$  = 0.65 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 48 nC)
- Low Crss (typical 21pF)
- · Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant



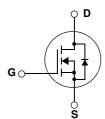
## **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.







# **Absolute Maximum Ratings**

Symbol	Parameter		FQP12N60C	FQPF12N60C	Unit	
V <sub>DSS</sub>	Drain-Source Voltage		600		V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 100°C)		12 12* 7.4 7.4*		A A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	48	48*	Α
V <sub>GSS</sub>	Gate-Source voltage		± 30		V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note:		(Note 2)	870		mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	12		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Not		(Note 1)	22.5		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C) - Derate above 25°C		225 1.78	51 0.41	W W/°C
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C	

<sup>\*</sup>Drain current limited by maximum junction temperature

## **Thermal Characteristics**

Symbol	Parameter	FQP12N60C	FQPF12N60C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.56	2.43	°C/W
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

# **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
FQP12N60C	FQP12N60C	TO-220	-	-	50
FQPF12N60C	FQPF12N60C	TO-220F	-	-	50

# **Electrical Characteristics** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter Conditions		Min	Тур	Max	Units
Off Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 250\mu A$ , $T_J = 25^{\circ}C$	600			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		0.5		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 480V, T <sub>C</sub> = 125°C	 		1 10	μ <b>Α</b> μ <b>Α</b>
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$ , $V_{DS} = 0V$			-100	nA
On Charac	teristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6A		0.53	0.65	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 6A (Note 4)		13		S
Dynamic C	haracteristics				•	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V,		1760	2290	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz		182	235	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			21	28	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 300V, I <sub>D</sub> = 12A		30	70	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25\Omega$		85	180	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			140	280	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		90	190	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 400V, I <sub>D</sub> = 12A		48	63	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10V		8.5		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4, 5)		21		nC
Drain-Sour	ce Diode Characteristics and Maximur	n Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				12	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V$ , $I_S = 12A$			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0V, I_{S} = 12A$		420		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s $ (Note 4)		4.9		μС

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 11mH, I $_{AS}$  = 12A, V $_{DD}$  = 50V, R $_{G}$  = 25 $\Omega$ , Starting T $_{J}$  = 25°C
- 3. I\_{SD}  $\leq$  12A, di/dt  $\leq$  200A/µs, V\_{DD}  $\leq$  BV\_DSS, Starting T\_J = 25°C
- 4. Pulse Test: Pulse width  $\leq 300 \mu s, \, \text{Duty Cycle} \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

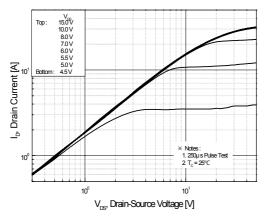
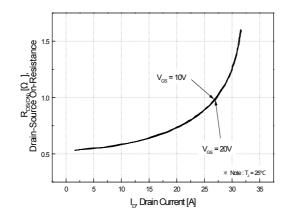


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage



**Figure 5. Capacitance Characteristics** 

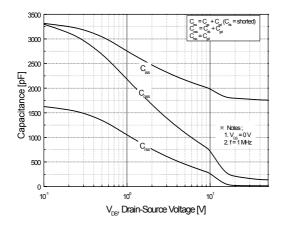


Figure 2. Transfer Characteristics

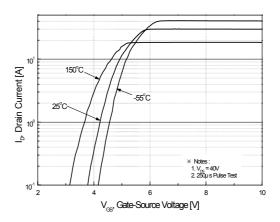


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

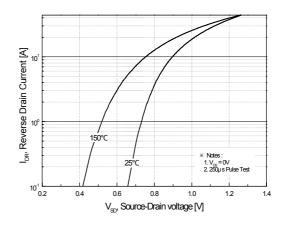
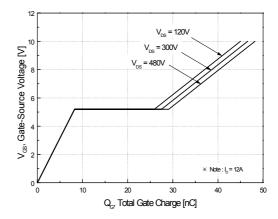


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

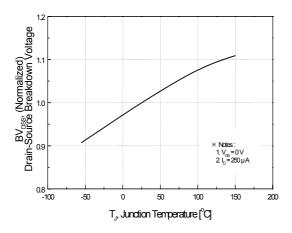


Figure 9-1. Maximum Safe Operating Area for FQP12N60C

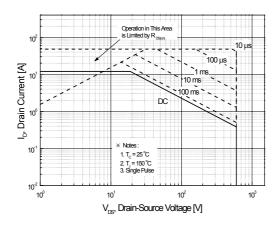


Figure 10. Maximum Drain Current vs. Case Temperature

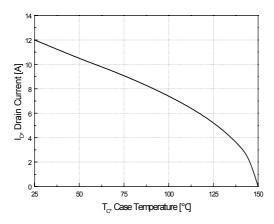


Figure 8. On-Resistance Variation vs. Temperature

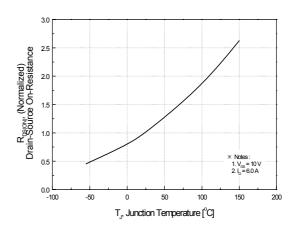
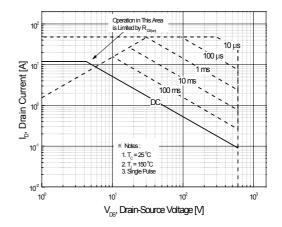


Figure 9-2. Maximum Safe Operating Area for FQPF12N60C



# Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve for FQP12N60C

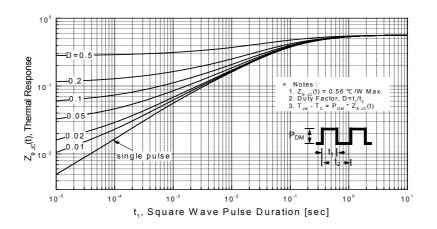
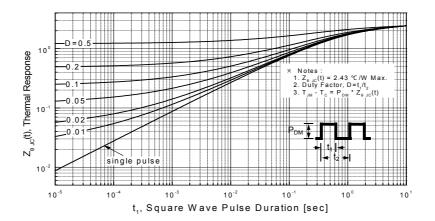
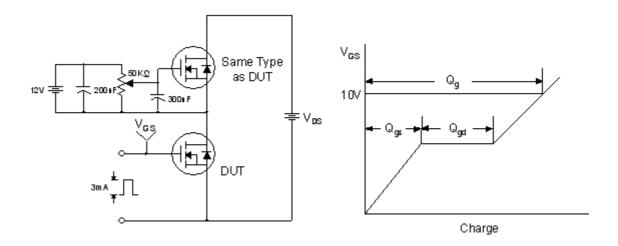


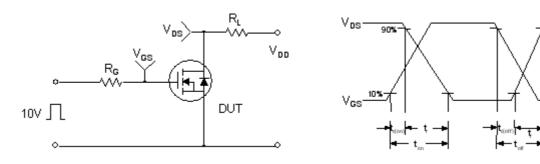
Figure 11-2. Transient Thermal Response Curve for FQPF12N60C



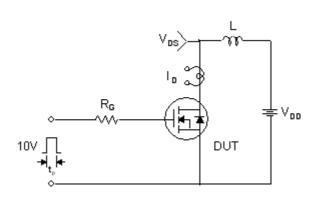
#### **Gate Charge Test Circuit & Waveform**

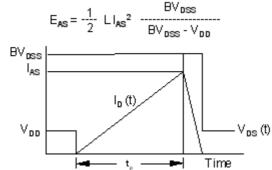


#### **Resistive Switching Test Circuit & Waveforms**

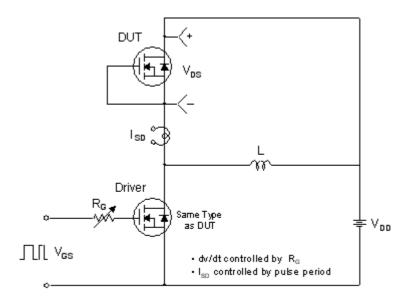


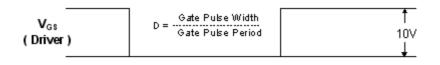
#### **Unclamped Inductive Switching Test Circuit & Waveforms**

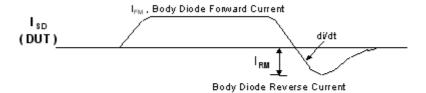


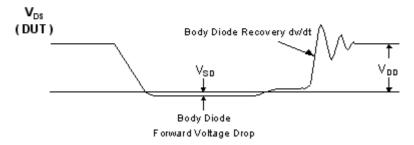


#### Peak Diode Recovery dv/dt Test Circuit & Waveforms



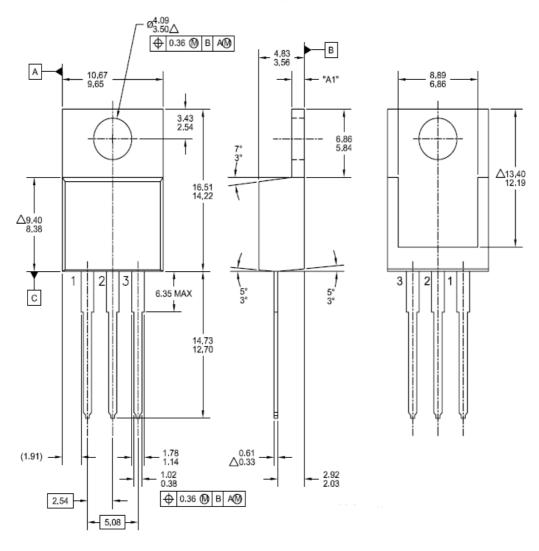


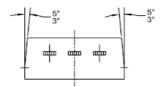




## **Mechanical Dimensions**

# TO - 220

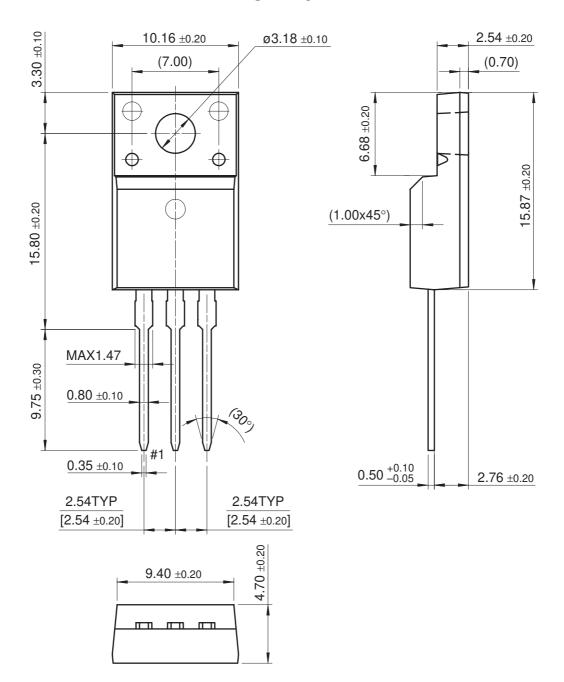




Dimensions in Millimeters

# Mechanical Dimensions (continued)

# TO-220F



Dimensions in Millimeters





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